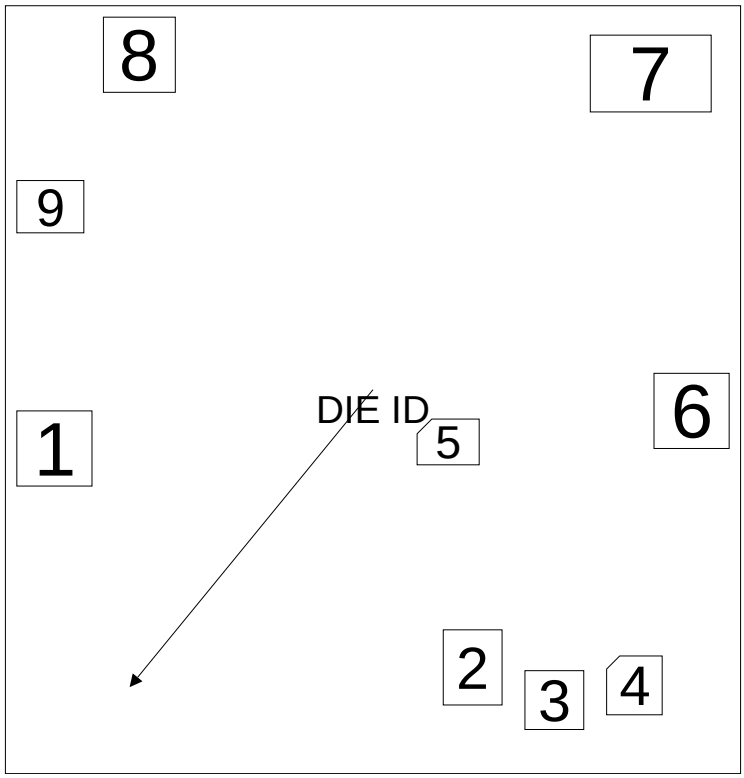
LM136-2.5 MDR
VOLTAGE REFERENCE DIODE

14-Aug-2012

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	136BJ 2.5	Bond Pad Opening Size (min)	111.76µm x 116.84µm
Die Step	B	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	152.4mm	Back Side Metal	Gold Back
Die Size (Drawn)	1143.00µm x 1193.80µm 45.0mils x 47.0mils	Back Side Connection	Floating
Thickness	0.0µm Nominal		
Min Pitch	626.23µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(B-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
ADJ	1	-495.30	-91.44	116.84	x	116.84
NC	2	154.94	-431.80	91.44	x	116.84
NC	3	281.94	-482.60	91.44	x	91.44
NC	4	406.40	-459.74	86.36	x	91.44
NC	5	116.84	-81.28	96.52	x	71.12
+	6	495.30	-33.02	116.84	x	116.84
NC	7	431.80	491.49	187.96	x	119.38
-	8	-363.22	520.70	111.76	x	116.84
NC	9	-501.65	284.48	104.14	x	81.28

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Notes

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